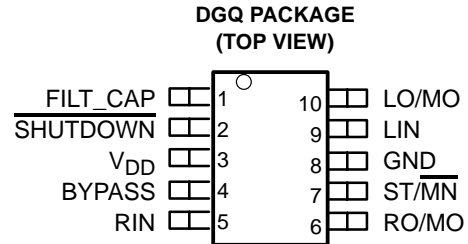


TPA0243

2-W MONO AUDIO POWER AMPLIFIER WITH HEADPHONE DRIVE

SLOS279C – JANUARY 2000 – REVISED NOVEMBER 2002

- Ideal for Notebook Computers, PDAs, and Other Small Portable Audio Devices
- 2 W Into 4-Ω From 5-V Supply
- 0.6 W Into 4-Ω From 3-V Supply
- Stereo Head Phone Drive
- Mono (BTL) Signal Created by Summing Left and Right Signals
- Wide Power Supply Compatibility
3 V to 5 V
- Meets PC99 Desktop Specs (target)
- Low Supply Current
 - 10 mA Typical at 5 V
 - 9 mA Typical at 3 V
- Shutdown Control . . . 1 μA Typical
- Shutdown Pin Is TTL Compatible
- –40°C to 85°C Operating Temperature Range
- Space-Saving, Thermally-Enhanced MSOP Packaging



description

The TPA0243 is a 2-W mono bridge-tied-load (BTL) amplifier designed to drive speakers with as low as 4-Ω impedance. The mono signal is created by summing left and right inputs. The amplifier can be reconfigured on the fly to drive two stereo single-ended (SE) signals into headphones. This makes the device ideal for small notebook computers, PDAs, digital personal audio players, anyplace a mono speaker and stereo headphones are required. From a 5-V supply, the TPA0243 can deliver 2 W of power into a 4-Ω speaker.

The gain of the input stage is set by the user-selected input resistor and a 50-kΩ internal feedback resistor ($A_V = -R_F/R_I$). The power stage is internally configured with a gain of –1.25 V/V in SE mode, and –2.5 V/V in BTL mode. Thus, the overall gain of the amplifier is 62.5 kΩ/ R_I in SE mode and 125 kΩ/ R_I in BTL mode. The input terminals are high-impedance CMOS inputs, and can be used as summing nodes.

The TPA0243 is available in the 10-pin thermally-enhanced MSOP package (DGQ) and operates over an ambient temperature range of –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

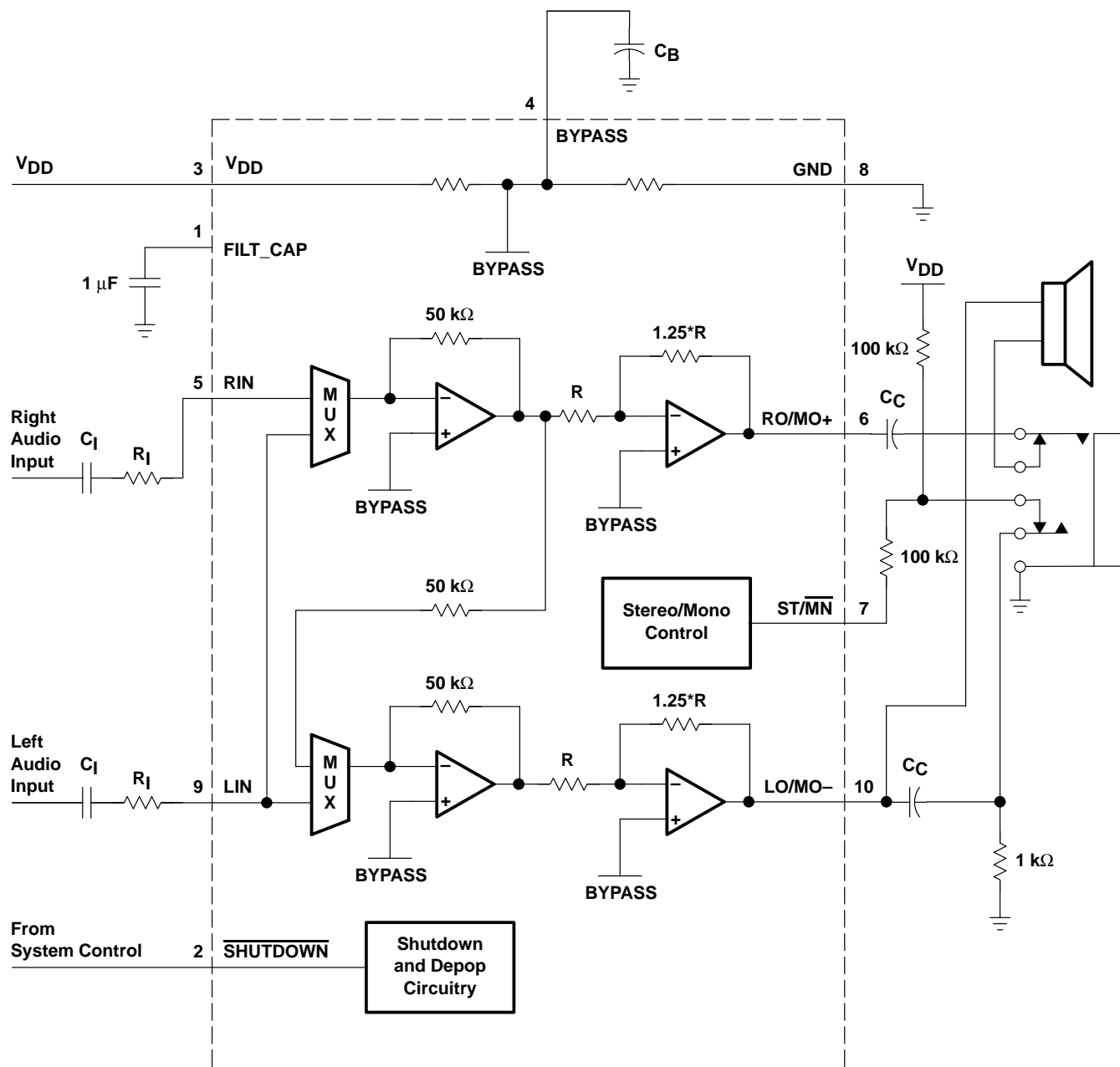
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AVAILABLE OPTIONS

T _A	PACKAGED DEVICES	MSOP SYMBOLIZATION
	MSOP† (DGQ)	
-40°C to 85°C	TPA0243DGQ	AEK

† The DGQ package are available taped and reeled. To order a taped and reeled part, add the suffix R to the part number (e.g., TPA0243DGQR).

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Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
BYPASS	4	I	BYPASS is the tap to the voltage divider for internal mid-supply bias. This terminal should be connected to a 0.1- μ F to 1- μ F capacitor.
GND	8		Ground terminal
LIN	9	I	Left-channel input terminal
LO/MO	10	O	Left-output in SE mode and mono negative output in BTL mode.
MONO-IN	1	I	Terminal used to filter supply
RIN	5	I	Right-channel input terminal
RO/MO	6	O	Right-output in SE mode and mono positive output in BTL mode
SHUTDOWN	2	I	SHUTDOWN places the entire device in shutdown mode when held low. TTL compatible input.
ST/MN	7	I	Selects between Stereo and Mono mode. When held high, the amplifier is in SE stereo mode; while held low, the amplifier is in BTL mono mode.
V _{DD}	3	I	V _{DD} is the supply voltage terminal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{DD}	6 V
Input voltage range, V _I	–0.3 V to V _{DD} +0.3 V
Continuous total power dissipation	internally limited (see Dissipation Rating Table)
Operating free-air temperature range, T _A (see Table 3)	–40°C to 85°C
Operating junction temperature range, T _J	–40°C to 150°C
Storage temperature range, T _{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C	DERATING FACTOR	T _A = 70°C	T _A = 85°C
DGQ	2.14 W [‡]	17.1 mW/°C	1.37 W	1.11 W

[‡] See *PowerPAD Thermally Enhanced Package Application Report (SLMA002)* for more information on the PowerPAD™ package. The thermal data was measured on a PCB layout based on the information in the section entitled *Texas Instruments Recommended Board for PowerPAD* on page 33 of that document.

recommended operating conditions

			MIN	MAX	UNIT
Supply voltage, V _{DD}			2.5	5.5	V
High-level input voltage, V _{IH}	ST/MN	V _{DD} = 3 V	2.7	V	
		V _{DD} = 5 V	4.5		
	SHUTDOWN		2		
Low-level input voltage, V _{IL}	ST/MN	V _{DD} = 3 V	1.65	V	
		V _{DD} = 5 V	2.75		
	SHUTDOWN		0.8		
Operating free-air temperature, T _A			−40	85	°C

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electrical characteristics at specified free-air temperature, $V_{DD} = 3\text{ V}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$ V_{OO} $ Output offset voltage (measured differentially)	$\overline{\text{SHUTDOWN}} = 2\text{ V}$, $\overline{\text{ST/MN}} = 0$, $R_L = 4\ \Omega$			30	mV
I_{DD} Supply current	$V_{DD} = 2.5\text{ V}$, $\overline{\text{SHUTDOWN}} = 2\text{ V}$		9	14	mA
$I_{DD}(\text{SD})$ Supply current, shutdown mode	$\overline{\text{SHUTDOWN}} = 0\text{ V}$		1	10	μA
$ I_{IH} $ High-level input current	$\overline{\text{SHUTDOWN}}$, $V_{DD} = 3.3\text{ V}$, $V_I = V_{DD}$			1	μA
	$\overline{\text{ST/MN}}$, $V_{DD} = 3.3\text{ V}$, $V_I = V_{DD}$			1	
$ I_{IL} $ Low-level input current	$\overline{\text{SHUTDOWN}}$, $V_{DD} = 3.3\text{ V}$, $V_I = 0\text{ V}$			1	μA
	$\overline{\text{ST/MN}}$, $V_{DD} = 3.3\text{ V}$, $V_I = 0\text{ V}$			1	
R_F Feedback resistor	$V_{DD} = 2.5\text{ V}$, $R_L = 4\ \Omega$, $\overline{\text{ST/MN}} = 1.375\text{ V}$, $\overline{\text{SHUTDOWN}} = 2\text{ V}$	47	50	57	k Ω

operating characteristics, $V_{DD} = 3\text{ V}$, $T_A = 25^\circ\text{C}$, $R_L = 4\ \Omega$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
P_O Output power, see Note 1	THD = 1%, BTL mode		660		mW
	THD = 0.1%, SE mode, $R_L = 32\ \Omega$		34		
THD + N Total harmonic distortion plus noise	$P_O = 500\text{ mW}$, $f = 20\text{ Hz to } 20\text{ kHz}$		0.3%		
BOM Maximum output power bandwidth	Gain = 2, THD = 2%		20		kHz

NOTE 1: Output power is measured at the output terminals of the device at $f = 1\text{ kHz}$.

electrical characteristics at specified free-air temperature, $V_{DD} = 5\text{ V}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$ V_{OO} $ Output offset voltage (measured differentially)	$\overline{\text{SHUTDOWN}} = 2\text{ V}$, $\overline{\text{ST/MN}} = 0$, $R_L = 4\ \Omega$			30	mV
I_{DD} Supply current	$\overline{\text{SHUTDOWN}} = 2\text{ V}$		10	15	mA
$I_{DD}(\text{SD})$ Supply current, shutdown mode	$\overline{\text{SHUTDOWN}} = 0\text{ V}$		1	10	μA
$ I_{IH} $ High-level input current	$\overline{\text{SHUTDOWN}}$, $V_{DD} = 5.5\text{ V}$, $V_I = V_{DD}$			1	μA
	$\overline{\text{ST/MN}}$, $V_{DD} = 5.5\text{ V}$, $V_I = V_{DD}$			1	
$ I_{IL} $ Low-level input current	$\overline{\text{SHUTDOWN}}$, $V_{DD} = 5.5\text{ V}$, $V_I = 0\text{ V}$			1	μA
	$\overline{\text{ST/MN}}$, $V_{DD} = 5.5\text{ V}$, $V_I = 0\text{ V}$			1	

operating characteristics, $V_{DD} = 5\text{ V}$, $T_A = 25^\circ\text{C}$, $R_L = 4\ \Omega$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
P_O Output power, see Note 1	THD = 1%, BTL mode		2		W
	THD = 0.1%, SE mode, $R_L = 32\ \Omega$		95		mW
THD + N Total harmonic distortion plus noise	$P_O = 1\text{ W}$, $f = 20\text{ Hz to } 20\text{ kHz}$		0.2%		
BOM Maximum output power bandwidth	Gain = 2.5, THD = 2%		20		kHz

NOTE 1: Output power is measured at the output terminals of the device at $f = 1\text{ kHz}$.



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPA0243DGQ	ACTIVE	MSOP-PowerPAD	DGQ	10		TBD	Call TI	Call TI	-40 to 125	AEK	Samples
TPA0243DGQG4	ACTIVE	MSOP-PowerPAD	DGQ	10		TBD	Call TI	Call TI	-40 to 125	AEK	Samples
TPA0243DGQR	ACTIVE	MSOP-PowerPAD	DGQ	10		TBD	Call TI	Call TI	-40 to 125	AEK	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

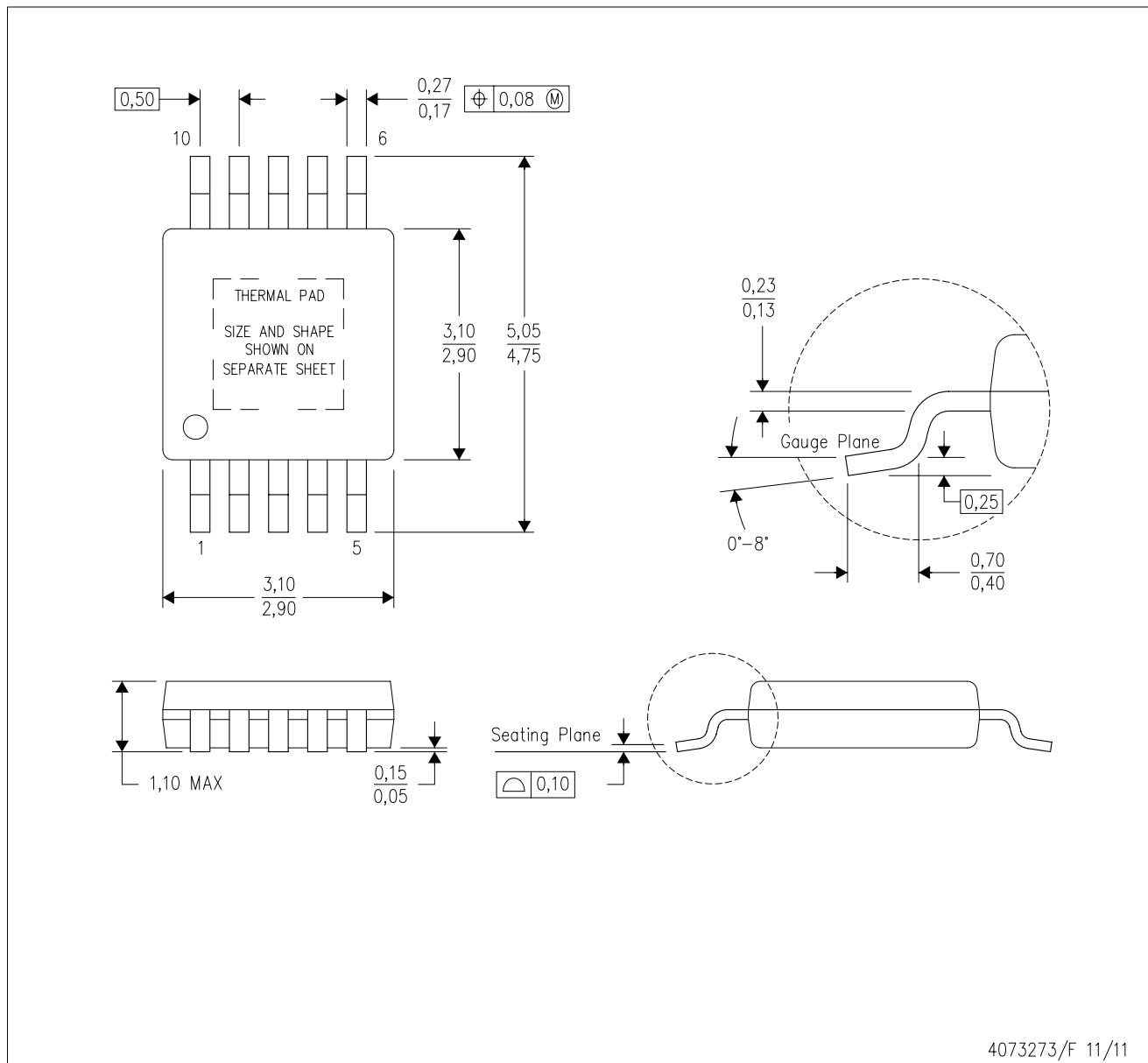
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DGQ (S-PDSO-G10)

PowerPAD™ PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <<http://www.ti.com>>.
 - E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - F. Falls within JEDEC MO-187 variation BA-T.

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